

This listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS:

1. (Currently amended) A photosensitive film which comprises a support film (A), a photosensitive resin composition-containing photosensitive resin layer (B) formed on said support film (A), and a protecting film (C) stuck onto said photosensitive resin layer (B), wherein:

the number of fish eyes having a diameter of at least 80 μm included in said protecting film (C) does not exceed 5 fish eyes/ m^2 when measured under a microscope at a multiplication of 100; and

said photosensitive resin composition-containing photosensitive resin layer (B) has a film thickness of 5 to 30 μm , and whereby

generation of air voids is reduced between the photosensitive layer (B) and a substrate after the photosensitive film is laminated on the substrate after removal of the protecting film (C) from the photosensitive film.

2. (Previously presented) A photosensitive film according to Claim 1, wherein the photosensitive resin composition in said photosensitive resin layer (B) comprises:

- (a) a binder polymer formed by copolymerizing acrylic acid or methacrylic acid and alkyl esters thereof as constituent monomers;
- (b) a monomer having at least one polymerizable ethylenically unsaturated group in the molecule thereof; and
- (c) a photopolymerization initiator.

3. (Previously presented) A photosensitive film according to Claim 1, wherein the adhesive strength between the photosensitive resin composition-containing photosensitive resin layer (B) and the support film (A) is greater than adhesive strength between the photosensitive resin composition-containing photosensitive resin layer (B) and the protecting film (C).

4. (Original) A photosensitive film according to claim 3, wherein said protecting film is a polypropylene film.

5. (Original) A photosensitive film according to claim 1, wherein said photosensitive film is for use in metal etching process.

6. (Original) A photosensitive film according to claim 1, wherein said photosensitive resin layer has a viscosity of 15 to 50 Mpa·s at 30°C.

7. (Original) A photosensitive film according to claim 1, wherein said protecting film has a thickness of 5 to 50 μ m.

8. (Previously presented) A photosensitive film according to Claim 2, wherein said binder polymer (a) contains a carboxyl group-containing monomer in an amount of 12 to 40% by weight based on the total amount of the monomers, has a weight-average molecular weight of 20,000 to 300,000, and is used in an amount of 40 to 80 parts by weight; wherein said monomer (b) is used in an amount of 20 to 60 parts by weight; and wherein said

photopolymerization initiator (c) is used in an amount of 0.1 to 20 parts by weight, based on 100 parts by weight of the total amounts of (a) and (b).

9. (Previously presented) A photosensitive film according to Claim 1, wherein the support film (A) has a film thickness of 12 to 25 μ m.

10. (Previously presented) A photosensitive film according to Claim 2, wherein the binder polymer (a) contains methacrylic acid as a constituting monomer.

11. (Previously presented) A photosensitive film according to Claim 2, wherein the monomer (b) is bisphenol A polyoxyalkylene diacrylate, or contains bisphenol A polyoxyalkylene dimethacrylate as a component.

12. (Previously presented) A photosensitive film according to Claim 2, wherein the photopolymerization initiator (c) contains 2,4,5-triarylimidazole dimer.

13. (Previously presented) A photosensitive film according to Claim 1, wherein said photosensitive resin layer (b) has a film thickness in a range of 10-25 μ m.

14. (Previously presented) A photosensitive film according to Claim 1, wherein the height of each fish eye, protruding from a surface of the protecting film, is in a range of 1-50 μ m.

15. (Currently amended) A process for laminating a photosensitive film on a substrate having a metallic surface, which comprises laminating a photosensitive film of Claim 1 on a substrate, while removing the protective film (C) so as to make the photosensitive resin layer (B) adhere to the substrate, wherein generation of air voids is reduced between the photosensitive resin later (B) and the substrate.

16. (Previously presented) A photosensitive resin layer laminated substrate obtained by the process of Claim 15.

17. (Previously presented) A process for curing a photosensitive resin layer, which comprises exposing the photosensitive resin layer laminated substrate of Claim 16 to light.

18. (Previously presented) A photosensitive film according to Claim 1, wherein the protecting film (C) is a film that can be removed at a time of lamination of the photosensitive film on a substrate.

19. (Currently amended) A photosensitive film comprising a support film, a photosensitive resin layer on said support film, and a protecting film stuck onto said photosensitive resin layer, wherein the protecting film has fish eyes of a diameter of at least 80 μ m in a number not exceeding 5 per square meter when measured under a microscope at a multiplication of 100, and whereby generation of air voids is reduced between the

photosensitive resin layer and a substrate after the photosensitive film is laminated on the substrate after removal of the protecting film from the photosensitive film.

20. (Canceled)

21. (Previously presented) A photosensitive film according to Claim 19, wherein adhesive strength between the photosensitive resin layer and the support film is greater than adhesive strength between the photosensitive resin layer and the protecting film.

22. (Previously presented) A photosensitive film according to Claim 19, wherein the support film has a film thickness of 12 to 25 μ m.

23. (Previously presented) A photosensitive film according to Claim 19, wherein the photosensitive resin layer is made from a resin composition comprising:

- (a) a binder polymer formed by copolymerizing acrylic acid or methacrylic acid and alkyl esters thereof as constituent monomers;
- (b) a monomer having at least one polymerizable ethylenically unsaturated group in the molecule thereof; and
- (c) a photopolymerization initiator.

24. (Previously presented) A photosensitive film according to Claim 23, wherein the binder polymer (a) contains a carboxyl group-containing monomer in an amount of 12 to 40% by weight based on the total amount of the monomers, has a weight-average molecular

weight of 20,000 to 300,000, and is used in an amount of 40 to 80 parts by weight; wherein the monomer (b) is used in an amount of 20 to 60 parts by weight; and wherein the photopolymerization initiator (c) is used in an amount of 0.1 to 20 parts by weight, based on 100 parts by weight of the total amounts of (a) and (b).

25. (Previously presented) A photosensitive film according to Claim 23, wherein the binder polymer (a) contains methacrylic acid as a constituent monomer.

26. (Previously presented) A photosensitive film according to Claim 23, wherein the monomer (b) is bisphenol A polyoxyalkylene diacrylate or contains bisphenol A polyoxyalkylene dimethacrylate as a component.

27. (Previously presented) A photosensitive film according to Claim 23, wherein the photopolymerization initiator (c) contains 2,4,5-triarylimidazole dimer.

28. (Previously presented) A photosensitive film according to Claim 19, wherein the protecting film is a polypropylene film.

29. (Previously presented) A photosensitive film according to Claim 19, wherein the photosensitive film is a film for use in a metal etching process.

30. (Previously presented) A photosensitive film according to Claim 19, wherein the photosensitive resin layer has a viscosity of 15 to 50 Mpa·s at 30°C.

31. (Previously presented) A photosensitive film according to Claim 19, wherein the protecting film has a thickness of 5 to 50 μ m.

32. (Previously presented) A photosensitive film according to Claim 19, wherein the protecting film is a film removed at a time of lamination of the photosensitive film on a substrate.

33. (Previously presented) A process for laminating a photosensitive film on a substrate, which comprises laminating the photosensitive film of Claim 19 on a substrate, while removing the protecting film so as to make the photosensitive resin layer adhere to the substrate having a metallic surface.

34. (Previously presented) A photosensitive resin layer laminated substrate obtained by the process of Claim 33.

35. (Previously presented) A process for curing a photosensitive layer, which comprises exposing the photosensitive resin layer laminated substrate of Claim 34 to light.

36. (Previously presented) A photosensitive film which comprises a support film (A), a photosensitive resin composition-containing photosensitive resin layer (B) formed on said support film (A), and a protecting film (C) stuck onto said photosensitive resin layer (B), wherein the number of fish eyes having a diameter of at least 80 μ m included in said

protecting film (C) does not exceed 5 fish eyes/m² when measured under a microscope at a multiplication of 100; and said photosensitive resin composition-containing photosensitive resin layer (B) has a film thickness of 5 to 30 μm , wherein generation of air voids is reduced after laminating the photosensitive film on a substrate after removal of the protecting film (C) from the photosensitive film in said photosensitive resin composition-containing photosensitive resin layer (B) does not exceed 5 air voids/m² when measured under a microscope at a multiplication of 100 following lamination of the photosensitive film and removal of the protecting film.

37. (new) A photosensitive film according to claim 1, wherein substantially no fish eyes are disposed in the protective film.